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You are warmly invited to the IEEE International Ultrasonics Symposium 2027, to be held in Singapore – a vibrant, world-class city at the crossroads of East and West. As one of Asia's leading hubs for science, technology, and research, Singapore offers an inspiring backdrop for the exchange of groundbreaking ideas, alongside a rich cultural experience, celebrated cuisine, and world-class connectivity that makes it one of the most welcoming destinations in the world. A vibrant ultrasonics eco-system is growing in Singapore, comprising multiple research institutes in A*STAR, local universities, hospitals and industry. We are looking forward to an unforgettable fruitful scientific and cultural experience together with all the professionals and students joining IUS 2027 in Singapore.

SUBMISSION TOPICS

Abstracts should be submitted according to the information posted on the conference web page. Each abstract will receive careful review and evaluation by the symposium Technical Program Committee based on originality of the work, contribution to the state of the art and overall interest to the ultrasonics community. Papers are solicited describing original work in the field of ultrasonics.

- » Group 1: Medical Ultrasonics
- » Group 2: Sensors, NDE & Industrial Applications
- » Group 3: Physical Acoustics
- » Group 4: Microacoustics – SAW, FBAR & MEMS
- » Group 5: Transducers & Transducer Materials
- » Special Interest Topics
 - Ultrasound wearables
 - Ultrasound neuromodulation

STUDENT PAPER COMPETITION AND TRAVEL SUPPORT

Students submitting abstracts are invited to participate in a student paper competition. To participate, the student must be the lead author and present their paper. Limited funds are available to support travel for IEEE UFFC student member attendees at the 2027 symposium. Awards will be given on a competitive basis.

KEY DATES

Abstract Submission Deadline
April 18, 2027

Acceptance Notification
June 7, 2027

Author Notification
June 14, 2027

Publication Submission
August 22, 2027

Conference Dates
September 12-15, 2027